GOOD-ARK

FH5 thru FH7

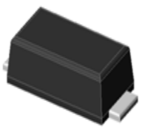
Surface Mount Glass Passivated High Efficiency Rectifier

Reverse Voltage 600~1000V   Forward Current 1A

Features

- Glass passivated High Efficiency Rectifiers
- Very low profile - typical height of 1.0 mm
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- AEC-Q101 qualified
- High temperature soldering guaranteed: 260°C/10 seconds
- Halogen-free according to IEC 61249-2-21 definition

RoHS COMPLIANT



eSGA
(SOD-123FL)

TYPICAL APPLICATIONS

For use of general purpose rectification in lighting, cellular phone, portable device, power supplies and other consumer applications.

MAXIMUM RATINGS (T$_A$ = 25 °C unless otherwise noted)

PARAMETER	SYMBOL	FH5	FH6	FH7	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	600	800	1000	V
Maximum RMS voltage	V_{RMS}	420	560	700	V
Maximum DC blocking voltage	V_{DC}	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	1.0			A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	30			A
Operating junction and storage temperature range	T_J, T_{STG}	- 55 to + 150			°C

ELECTRICAL CHARACTERISTICS (T$_A$ = 25 °C unless otherwise noted)

PARAMETER	TEST CONDITIONS	SYMBOL	FH5	FH6	FH7	UNIT
Maximum instantaneous forward voltage	1 A	V_F	1.7			Volts
Maximum DC reverse current at rated DC blocking voltage	TA=25℃ TA=125℃	I_R	5 100			µA
Maximum reverse recovery time	I_F=0.5A,I_R=1.0A, I_{rr}=0.25A	t_{rr}	75			nS
Typical junction capacitance	4.0 V, 1 MHz	C_J	15			pF
Typical thermal resistance 1)	juntion to ambient	$R_{θJA}$	66			℃/W
	juntion to case	$R_{θJC}$	28			
	juntion to mount	$R_{θJM}$	1			

Note:1),The thermal resistance from junction to ambient,case or mount,mounted on P.C.B with 5×5mm copper pads,2 OZ,FR4 PCB

RATINGS AND CHARACTERISTICS CURVES

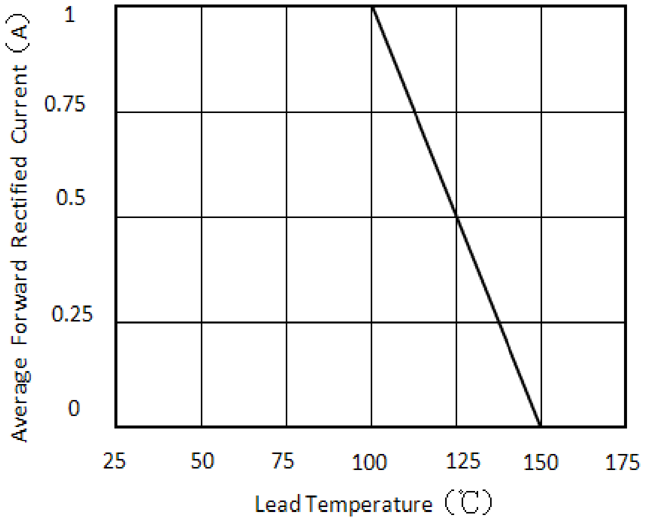


Figure 1.Forward Current Derating Curve

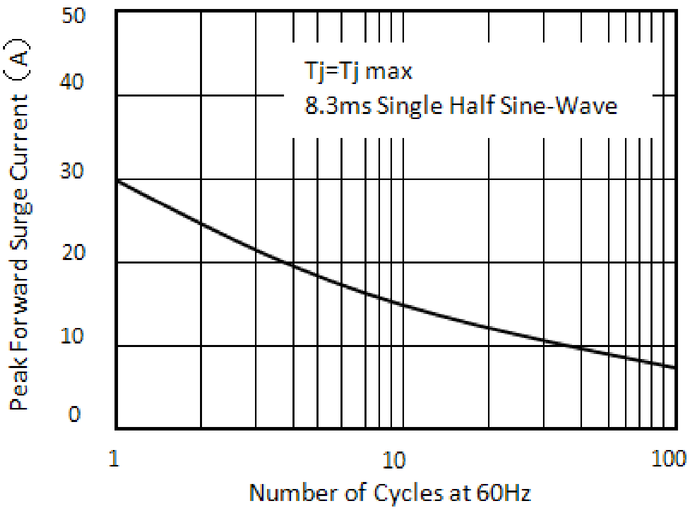


Figure 2.Maximum Non-Repetitive Peak Forward Surge Current

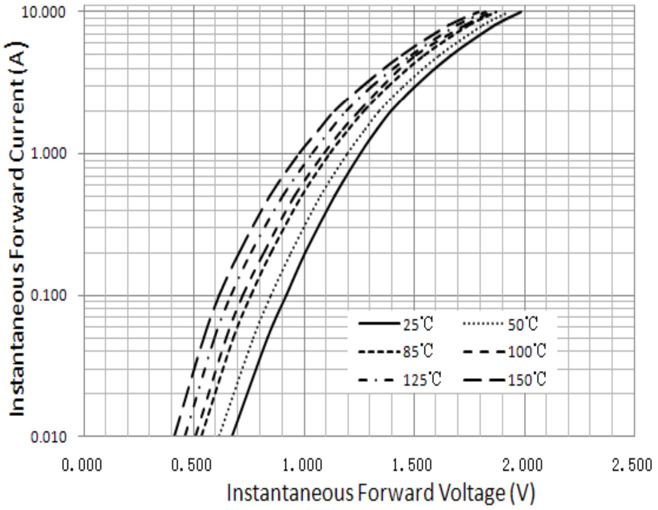


Figure 3. Typical Instantaneous Forward Characteristics

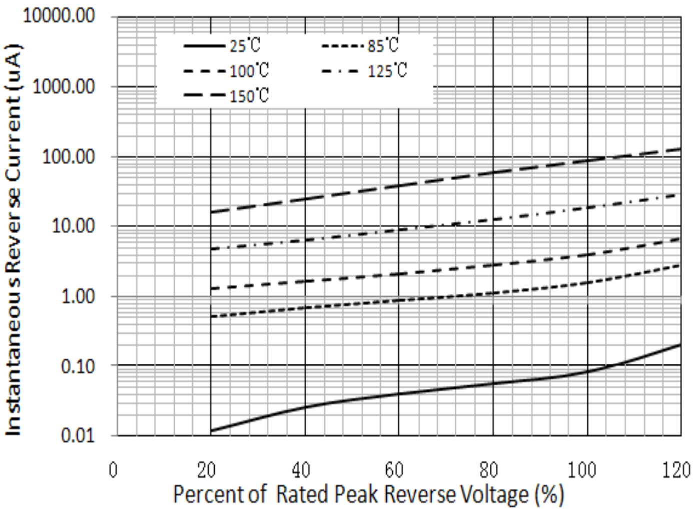


Figure 4. Typical Reverse Characteristics

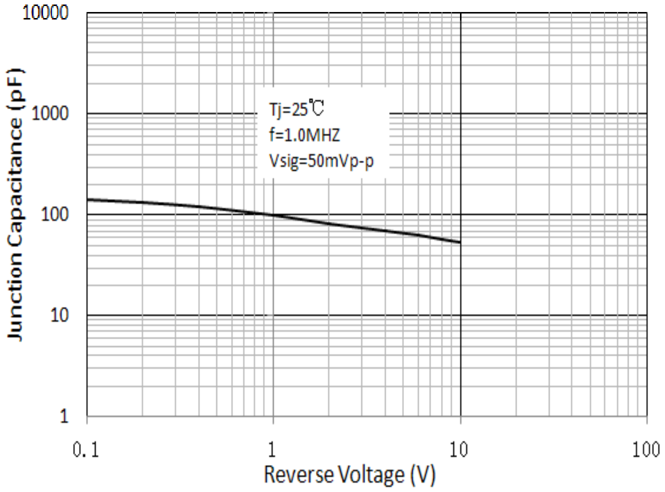
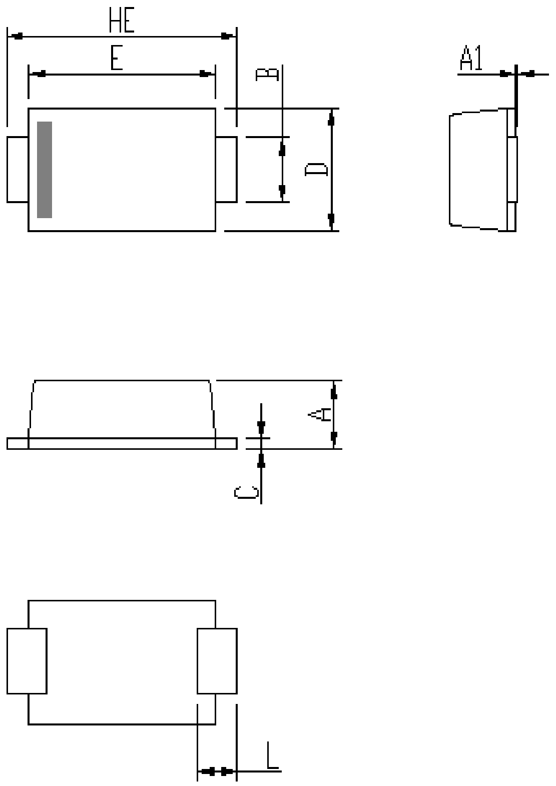


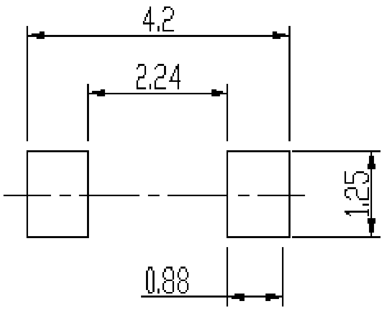
Figure 5. Typical Junction Capacitance

PACKAGE OUTLINE DIMENSIONS



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
A	0.9	1.08	0.035	0.043
A1	0	0.1	0.000	0.004
B	0.85	1.05	0.033	0.041
C	0.1	0.25	0.004	0.010
D	1.7	2	0.067	0.079
E	2.9	3.1	0.114	0.122
L	0.43	0.83	0.017	0.033
HE	3.5	3.9	0.138	0.154

Soldering footprint



PACKING INFORMATION

Packing quantities:

3000 pcs/Reel, 40 Reels/Box; 8mm Tape, 7" Reel

Tape & Reel Specification